

# High Voltage Standard Rectifier

3~ Rectifier	
$V_{RRM}$	= 2200 V
$I_{DAV}$	= 90 A
$I_{FSM}$	= 370 A

Half 3~ Bridge, Common Cathode

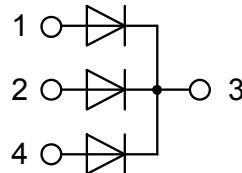
**Part number**

DNA90YC2200NA



Backside: isolated

E72873



**Features / Advantages:**

- Planar passivated chips
- Very low leakage current
- Very low forward voltage drop
- Improved thermal behaviour

**Applications:**

- Diode for main rectification
- For single and three phase bridge configurations

**Package:** SOT-227B (minibloc)

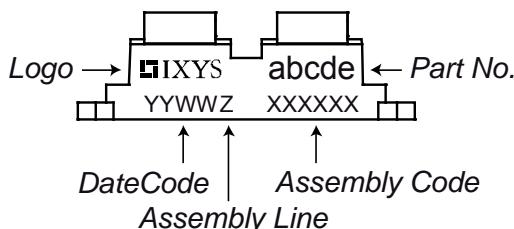
- Isolation Voltage: 3000 V~
- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0
- Base plate: Copper internally DCB isolated
- Advanced power cycling

## Rectifier

Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
$V_{RSM}$	max. non-repetitive reverse blocking voltage	$T_{VJ} = 25^\circ C$			2300	V
$V_{RRM}$	max. repetitive reverse blocking voltage	$T_{VJ} = 25^\circ C$			2200	V
$I_R$	reverse current, drain current	$V_R = 2200 V$ $V_R = 2200 V$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 150^\circ C$		100 1.5	$\mu A$ mA
$V_F$	forward voltage drop	$I_F = 30 A$ $I_F = 90 A$ $I_F = 30 A$ $I_F = 90 A$	$T_{VJ} = 25^\circ C$ $T_{VJ} = 125^\circ C$		1.23 1.70 1.21 1.85	V V
$I_{DAV}$	bridge output current	$T_C = 85^\circ C$ rectangular $d = \frac{1}{3}$	$T_{VJ} = 150^\circ C$		90	A
$V_{FO}$ $r_F$	threshold voltage slope resistance } for power loss calculation only		$T_{VJ} = 150^\circ C$		0.86 11.4	V $m\Omega$
$R_{thJC}$	thermal resistance junction to case				1.2	K/W
$R_{thCH}$	thermal resistance case to heatsink			0.10		K/W
$P_{tot}$	total power dissipation		$T_C = 25^\circ C$		100	W
$I_{FSM}$	max. forward surge current	$t = 10 ms; (50 Hz)$ , sine $t = 8,3 ms; (60 Hz)$ , sine	$T_{VJ} = 45^\circ C$ $V_R = 0 V$		370 400	A
		$t = 10 ms; (50 Hz)$ , sine $t = 8,3 ms; (60 Hz)$ , sine	$T_{VJ} = 150^\circ C$ $V_R = 0 V$		315 340	A
$I^2t$	value for fusing	$t = 10 ms; (50 Hz)$ , sine $t = 8,3 ms; (60 Hz)$ , sine	$T_{VJ} = 45^\circ C$ $V_R = 0 V$		685 665	$A^2s$
		$t = 10 ms; (50 Hz)$ , sine $t = 8,3 ms; (60 Hz)$ , sine	$T_{VJ} = 150^\circ C$ $V_R = 0 V$		495 480	$A^2s$
$C_J$	junction capacitance	$V_R = 700 V; f = 1 MHz$	$T_{VJ} = 25^\circ C$	7		pF

Package SOT-227B (minibloc)			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
$I_{RMS}$	RMS current	per terminal			150	A
$T_{stg}$	storage temperature		-40		150	°C
$T_{VJ}$	virtual junction temperature		-40		150	°C
Weight				30		g
$M_D$	mounting torque		1.1		1.5	Nm
$M_T$	terminal torque		1.1		1.5	Nm
$d_{Spp/App}$	creepage distance on surface   striking distance through air	terminal to terminal	10.5	3.2		mm
$d_{Spb/Abp}$		terminal to backside	8.6	6.8		mm
$V_{ISOL}$	isolation voltage	t = 1 second t = 1 minute 50/60 Hz, RMS; $I_{ISOL} \leq 1$ mA	3000 2500			V V

### Product Marking



### Part number

D = Diode  
 N = High Voltage Standard Rectifier  
 A = ( $\geq 2000$  V)  
 90 = Current Rating [A]  
 YC = Half 3~ Bridge, Common Cathode  
 2200 = Reverse Voltage [V]  
 NA = SOT-227B (minibloc)

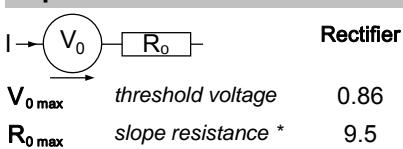
Ordering	Part Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DNA90YC2200NA	DNA90YC2200NA	Tube	10	513723

Similar Part	Package	Voltage class
DNA90YA2200NA	SOT-227B (minibloc)	2200

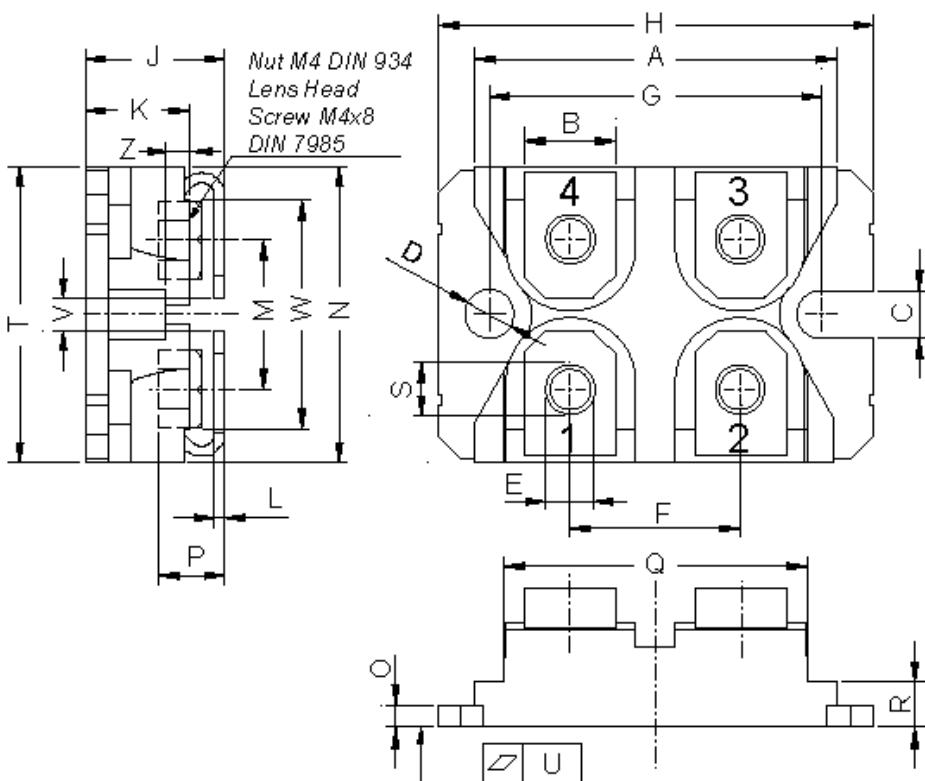
### Equivalent Circuits for Simulation

\* on die level

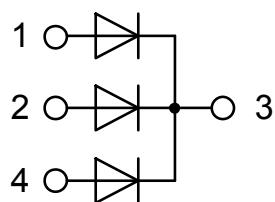
$T_{VJ} = 150$  °C



## Outlines SOT-227B (minibloc)



Dim.	Millimeter		Inches	
	min	max	min	max
A	31.50	31.88	1.240	1.255
B	7.80	8.20	0.307	0.323
C	4.09	4.29	0.161	0.169
D	4.09	4.29	0.161	0.169
E	4.09	4.29	0.161	0.169
F	14.91	15.11	0.587	0.595
G	30.12	30.30	1.186	1.193
H	37.80	38.23	1.488	1.505
J	11.68	12.22	0.460	0.481
K	8.92	9.60	0.351	0.378
L	0.74	0.84	0.029	0.033
M	12.50	13.10	0.492	0.516
N	25.15	25.42	0.990	1.001
O	1.95	2.13	0.077	0.084
P	4.95	6.20	0.195	0.244
Q	26.54	26.90	1.045	1.059
R	3.94	4.42	0.155	0.167
S	4.55	4.85	0.179	0.191
T	24.59	25.25	0.968	0.994
U	-0.05	0.10	-0.002	0.004
V	3.20	5.50	0.126	0.217
W	19.81	21.08	0.780	0.830
Z	2.50	2.70	0.098	0.106



## Rectifier

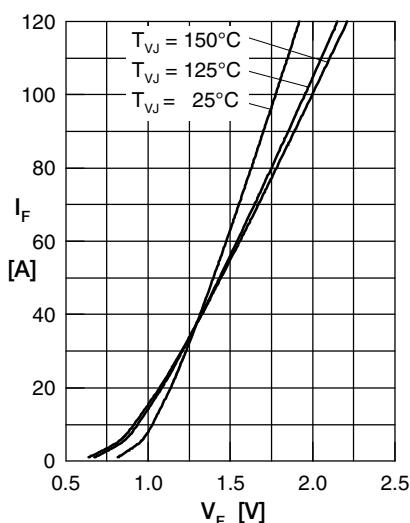


Fig. 1 Forward current versus voltage drop per diode

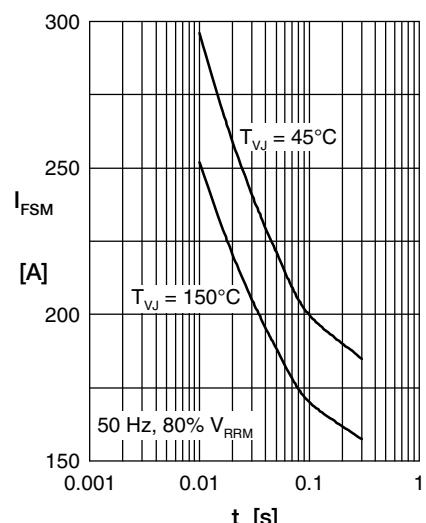


Fig. 2 Surge overload current

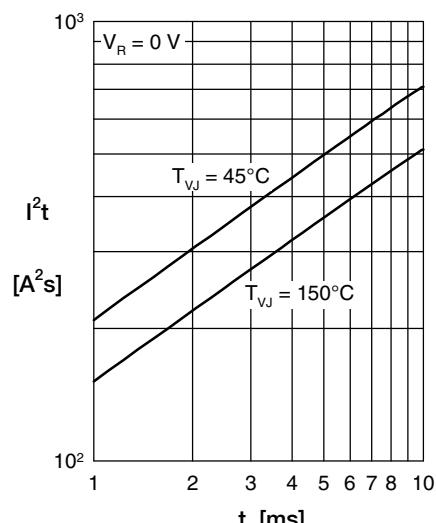
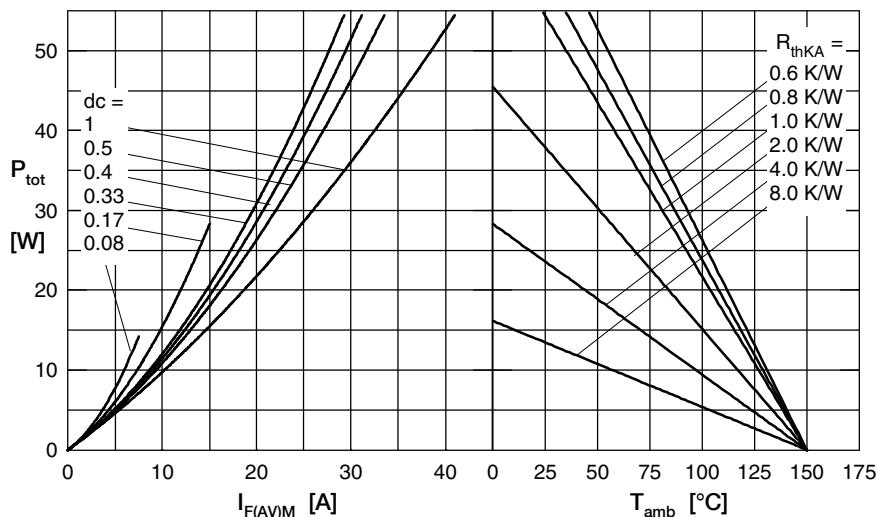
Fig. 3  $I^2t$  versus time per diode

Fig. 4 Power dissipation versus direct output current and ambient temperature

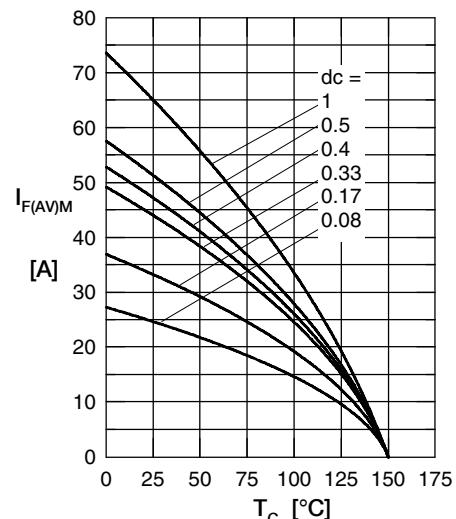


Fig. 5 Max. forward current versus case temperature

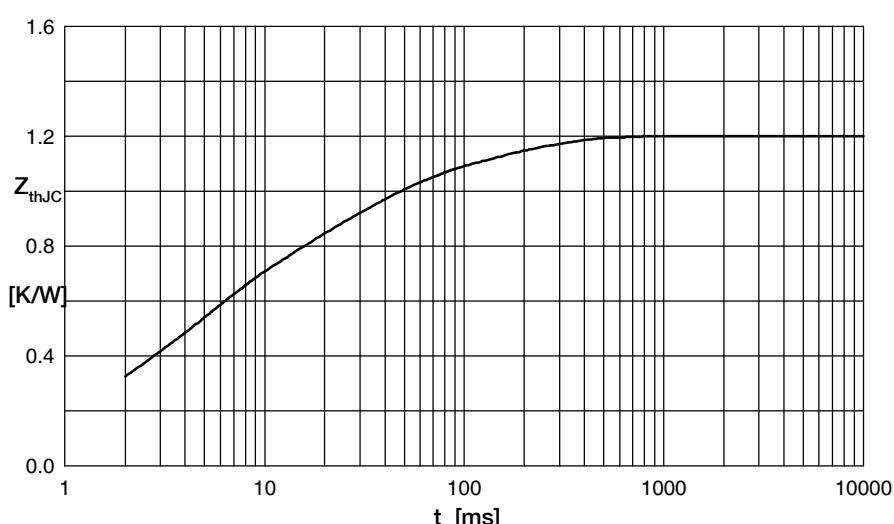


Fig. 6 Transient thermal impedance junction to case

Constants for  $Z_{thJC}$  calculation:

i	$R_{thi}$ (K/W)	$t_i$ (s)
1	0.06	0.0004
2	0.2	0.00265
3	0.34	0.0045
4	0.4	0.0242
5	0.2	0.15